



 MICROCHIP						Package Homogeneous Materials									
Semiconductor Device Type:			JANTX2N2222AUA												
Basic Substance	CAS Number	"Contained In" Sub-Component	% Total Weight	mg/part	ppm	92.08	(mg) Total	UA Base	% of Total Weight	67.62					
Ceramic	1344-28-1	UA Base	58.90	80.20000	588984		Ceramic	1344-28-1	87.10						
Tungsten	7440-33-7	UA Base	5.68	7.74000	56842		Tungsten	7440-33-7	8.41						
Tungsten	7440-33-7	UA Base	2.57	3.49800	25689		Tungsten	7440-33-7	3.80						
Gold	7440-57-5	UA Base	0.32	0.43500	3195		Gold	7440-57-5	0.47						
Nickel	7440-02-0	UA Base	0.15	0.20600	1513		Nickel	7440-02-0	0.22						
Oxynitride	112760-32-4	Die	0.00	0.00086	6	Total100.00									
Aluminum	7429-90-5	Die	0.00	0.00154	11										
Silicon	7440-21-3	Die	0.00	0.00002	0	0.207059	(mg) Total	Die	% of Total Weight	0.15					
Silicon	7440-21-3	Die	0.15	0.20200	1483		Oxynitride	112760-32-4	0.42						
Gold	7440-57-5	Die	0.00	0.00264	19		Aluminum	7429-90-5	0.75						
Iron	7439-89-6	UA Combo Lid	13.81	18.80000	138066		Silicon	7440-21-3	0.01						
Nickel	7440-02-0	UA Combo Lid	7.42	10.10000	74174		Silicon	7440-21-3	97.56						
Cobalt	7440-48-4	UA Combo Lid	4.35	5.93000	43550		Gold	7440-57-5	1.27						
Gold	7440-57-5	UA Combo Lid	0.70	0.94700	6955	Total100.00									
Nickel	7440-02-0	UA Combo Lid	0.64	0.87200	6404										
Gold	7440-57-5	UA Combo Lid	4.24	5.78000	42448	43.88	(mg) Total	UA Combo Lid	% of Total Weight	32.22					
Tin	7440-31-5	UA Combo Lid	1.06	1.45000	10649		Iron	7439-89-6	42.85						
Aluminum	7429-90-5	Bond Wire	0.00	0.00174	13		Nickel	7440-02-0	23.02						
TOTALS:			100.00	136.17	1,000,000		Cobalt	7440-48-4	13.51						
136.17 mg Total Mass															
The information contained in this Material Content Declaration (MCD) consists of package-level information and is not part number specific. This information is considered to be sufficiently representative of all part numbers for the package type.															
												Gold	7440-57-5	2.16	
												Nickel	7440-02-0	1.99	
												Gold	7440-57-5	13.17	
												Tin	7440-31-5	3.30	
											Total100.00				
											0.00	(mg) Total	Bond Wire	% of Total Weight	0.00
												Aluminum	7429-90-5	100.00	
											136.17	Total	Total	100.00	100.00
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